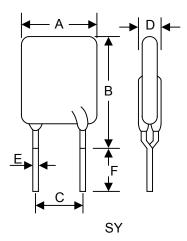


# **Positive Temperature Coefficient**

#### **Features**

- Radial leaded devices.
- Over-current protection
- High voltage surge capabilities
- Flame retardant epoxy polymer insulating material meets UL94 V-0 requirement.
- Available in lead-free version.
- Meets MSL level 1, per J-STD-020

#### **Dimensions (Unit: mm)**



Part	Α	В	С	D	E	F
Number	Max.	Max.	±0.6	Max.	Тур.	Min.
JK600-110	15.0	15.0	5.1	6.5	0.6	4.6
JK600-150	15.0	15.0	5.1	6.5	0.6	4.6
JK600-160	15.0	15.0	5.1	6.5	0.6	4.6

#### **Electrical Characteristics**

Part	Ι <sub>Η</sub>	I <sub>T</sub>	$V_{MAXi}$	I <sub>MAX</sub>	$R_{MAX}$	$R_{MIN}$	Pd <sub>typ.</sub>
Number	(A)	(A)	(V <sub>AC</sub> )	(A)	(Ω)	(Ω)	(W)
JK600-110	0.11	0.22	500	3	18.0	6.0	1.0
JK600-150	0.15	0.30	500	3	15.0	5.0	1.0
JK600-160	0.16	0.32	500	3	12.0	4.0	1.0

- $I_H$  = Hold current: maximum current device will pass without tripping in 25  $^{\circ}$ C still air.
- I<sub>T</sub> = Trip current: minimum current at which the device will trip in 25°C still air.
- V<sub>MAXi</sub> = Maximum interrupt voltage device can withstand without damage at rated current.
- $I_{\text{MAX}}$  = Maximum fault current device can withstand without damage at rated voltage.
- R<sub>MAX</sub> = Maximum resistance of device in initial (un-soldered) state.
- R<sub>MIN</sub> = Minimum resistance of device in initial (un-soldered) state.
- $\bullet$  Pd  $_{\mbox{\scriptsize typ.}}$  = Typical power dissipation from device when in the tripped state at 25  $^\circ\! {\rm C}$  still air.



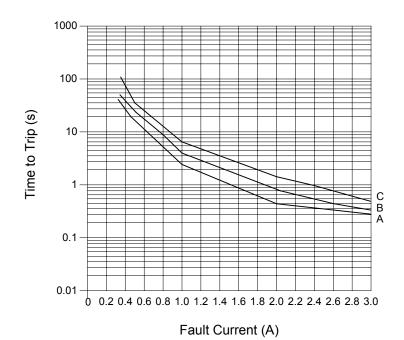
# Thermal Derating Chart – I<sub>H</sub> (A)

Part	Maximum Ambient Operating Temperatures (℃)								
Number	-20	0	25	30	40	50	60	70	85
JK600-110	0.152	0.131	0.110	0.100	0.091	0.080	0.070	0.061	0.046
JK600-150	0.207	0.179	0.150	0.137	0.125	0.110	0.096	0.083	0.063
JK600-160	0.221	0.190	0.160	0.146	0.133	0.117	0.102	0.088	0.067

### **Test Procedures and Requirement**

Items	Test Conditions	Accept/Reject Criteria	
Resistance	In still air @25℃	$R_{min} \le R \le R_{max}$	
Time to Trip	Specified current, V <sub>max</sub> , 25℃	$T \le max$ . Time to trip $(T_{trip})$	
Hold Current	30 min, at I <sub>H</sub>	No trip	
Trip Cycle Life	V <sub>max</sub> , I <sub>max</sub> , 100 cycles	No arcing or burning	
Trip Endurance	V <sub>max</sub> , 24hours	No arcing or burning	

### Typical Time-to-Trip Charts @25℃



A=JK600-110 B=JK600-150 C=JK600-160

# **Storage Recommendations**

■ Storage Temperature: -10°C~+40°C

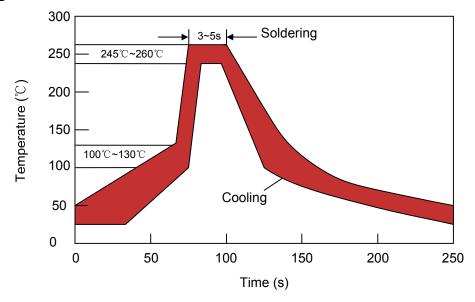
■ Relative Humidity: ≤80%RH

■ Keep away from corrosive atmosphere and sunlight.

■ Period of Storage: 1 year.



# **Wave Soldering Recommendation Parameters**



Items	Conditions
Pre-Heating Zone	Refer to the condition recommended by the flux manufacturer.  Maximum ramping rate should not exceed 4°C/sec.
Soldering Zone	Maximum solder temperature should not exceed 260 ℃
Cooling Zone	Forced cooling

# **Manual Soldering Recommendation Parameters**

Items	Conditions
Soldering condition	The highest power of the manual soldering iron should be 30W or less, soldering temperature should not be higher than 280 $^\circ$ C.
Soldering time	The soldering time should be kept within 3 seconds, otherwise it might cause insulation layer cracking, and increased part resistance.
Soldering position	The distance on the leads between the soldering point and bottom of the PPTC body should be equal or greater than 4mm.
Other	The soldering iron should not contact the PPTC body except the leads. If the soldering conditions are kept to lower temperature, less time and larger distance, the outcome of the soldering will be better.

Notes: 1. Before using the device must be stored in the original bags, if the storage conditions do not guarantee, the device may not be able to meet the given value.

2. The devices can't used for reflow soldering.



#### **Mechanical Characteristics**

Items	Specifications	Test Conditions/Methods	
Tensile strength	No visible damage	1.0Kgf, 10 seconds	
Bending strength	No visible damage	0.5Kgf, 90°, 3 times	
Vibration	No visible damage	Freq: 10-55Hz, Amp: 0.75mm, 1min	

# **Reliability Test**

Items	Specifications	Test Conditions/Methods
Solder ability	No visible damage,Solder OK, Solder area ≥95%	245±5℃, 2±1s, dipping depth=0.5inch max from the body
Resistance to soldering heat	No visible damage, Electrical OK, $ \Delta R/R0  \le 50\%$	260±5℃, 10+2/-0s
Damp heat, steady state	No visible damage, Electrical OK, ΔR/R0   ≦20%	40±2℃, 90~95 % RH, total 48Hrs, after 4Hrs test electrical parameter
Temperature cycling	No visible damage, Electrical OK,   ΔR/R0   ≦20%	Ta=-10+0/-1°C 30min, Ta=70+1/-0°C 30min, 5cycles, after 1hr test electrical parameter